



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Daniel Yap	)	Group Art No.: 2827
		)	
Application No:	10/053,159	)	Examiner: Thai, Luan C.
		)	
Filed:	01/15/2002	)	<b>Re: Rule 312 Amendment</b>
		)	
For:	"Precision Electroplated Solder Bumps..."	)	Our Ref: B-3752DIV 619413-2
		)	
		)	Date: March 4, 2004

Mail Stop Issue Fee  
Commissioner for Patents  
POB 1450  
Alexandria, VA 22313-1450

Dear Sir:

This paper is filed in Notice of Allowance dated December 5, 2003.

Amendments to the Claims are reflected in the listing of Claims, which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.